# GOMACTECH 2026

**NEW ORLEANS ERNEST N. MORIAL CONVENTION CENTER, NEW ORLEANS, LA**
**MARCH 9 - 12, 2026**

| | GOMACTech Timetable | 2nd Floor Foyer | Exhibit Hall I-2 | NOLA Theater Foyer | NOLA Theater Section B | Room 286-287 | Room 288-289 | Room 291-292 | Room 293 | Room 294 | Room 295 | Room 296 | GOMACTech Timetable | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **Sunday, March 8** | 6:00–8:00 pm | .............................. | .............................. | **Trusted Supplier Opening Networking Reception (All attendees)** | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | 6:00–8:00 pm | **Sunday, March 8** |
| **Monday, March 9** | 8:00 am–12:00 pm | **Registration (7:00 am–6:00 pm)** | .............................. | .............................. | | **Workshop:**<br>***Trusted Supplier Industry Day***<br>**(8:30 am–4:30 pm)** | .............................. | **Workshop:**<br>***Trusted & Assured Microelectronics Program*** | .............................. | .............................. | .............................. | .............................. | 8:00 am–12:00 pm | **Monday, March 9** |
| | 1:00–4:30 pm | | .............................. | .............................. | .............................. | | .............................. | **Workshop:**<br>***ME Evidence-Based Assurance*** | **Workshop:**<br>***Managing Cost and Complexity of Design Enablement in Collaborative R&D Environments*** | .............................. | .............................. | .............................. | 1:00–4:30 pm | |
| | 5:00–7:00 pm | | .............................. | **Welcome Reception - All Attendees (NOLA Theater Foyer)**<br>intel foundry | | | | | | | | | 5:00–7:00 pm | |
| **Tuesday, March 10** | 8:00–10:15 am | **Registration (7:00 am–6:00 pm)**<br>**Breakfast (7:00–7:45 am)** | .............................. | .............................. | **Plenary Session** | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | 8:00–10:15 am | **Tuesday, March 10** |
| | BREAK<br>10:15–10:30 am | | | **BREAK** | | | | | | | | | BREAK<br>(10:15–10:30 am) | |
| | 10:30 am–12:00 pm | | | .............................. | **Plenary Session** | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | 10:30 am–12:00 pm | |
| | LUNCH<br>12:00–1:30 pm | | .............................. | **LUNCH BUFFET (Exhibit Hall I-2)** | | | | | | | | | LUNCH<br>12:00–1:30 pm | |
| | 1:30–3:10 pm | | **Exhibits Open (12:00–8:00 pm)** | .............................. | .............................. | **Panel:**<br>***Technology Transition Strategies for High-Power RF Devices*** | **Session 1:**<br>Advanced RF Components & Devices | **Session 2:**<br>Hardware Trojans and Intellectual Property Protections | **Session 3:**<br>Chiplets | **Session 4:**<br>Packaging for Power Electronics | **Session 5:**<br>EDA for Next Generation Design | **Session 6:**<br>Superconducting Electronics Design and Architecture Constructs | 1:30–3:10 pm | |
| | BREAK<br>3:10–3:30 pm | | | **BREAK (Exhibit Hall I-2)** | | | | | | | | | BREAK<br>3:10–3:30 pm | |
| | 3:30–5:10 pm | | | .............................. | .............................. | **Panel:**<br>***VC Discussion on Accelerating Public Innovation with Private Capital*** | **Session 7:**<br>Canceller & Filter Technology | **Session 8:**<br>Counterfeit Devices and Supply Chains | **Session 9:**<br>3DHI Thermal Management Solutions | **Session 10:**<br>Advanced Power Electronics | **Session 11:**<br>Analog | **Session 12:**<br>Advanced Sensing Technologies | 3:30–5:10 pm | |
| | 6:00–8:00 pm | .............................. | .............................. | **EXHIBITOR RECEPTION (Exhibit Hall I-2)** | | | | | | | | | 6:00–8:00 pm | |
| **Wednesday, March 11** | 8:20–10:00 am | **Registration (7:00 am–6:00 pm)**<br>**Breakfast (7:30–8:30 am)** | .............................. | .............................. | .............................. | **Panel:**<br>***Obsolescence in Microelectronic Systems*** | **Session 13:**<br>Ultra-Wide Bandgap I | **Session 14:**<br>Hardware Assurance Capabilities | **Session 15:**<br>Design for 3DIC | **Session 16:**<br>SPCE | **Session 17:**<br>Advanced Digital Design | **Session 18:**<br>Quantum Architecture and Design | 8:20–10:00 am | **Wednesday, March 11** |
| | BREAK<br>10:00–10:30 am | | **Exhibits Open (9:00 am–4:00 pm)** | **BREAK (Exhibit Hall I-2)** | | | | | | | | | BREAK<br>10:00–10:30 am | |
| | 10:30 am–12:10 pm | | | .............................. | .............................. | **Panel:**<br>***Holistic Security for Microelectronics*** | **Session 19:**<br>Ultra-Wide Bandgap II | **Session 20:**<br>Cryptography | **Session 21:**<br>Heterogeneous Integration Technologies | **Session 22:**<br>Solid State Technology for High Voltage Pulsed Power Sources | **Session 23:**<br>Other Design | **Session 24:**<br>Photonic Integrated Circuits | 10:30 am–12:10 pm | |
| | LUNCH<br>12:10–1:30 pm | | | **LUNCH BUFFET (Exhibit Hall I-2)** | | | | | | | | | LUNCH<br>12:10–1:30 pm | |
| | 1:30–3:10 pm | | | .............................. | .............................. | **Panel:**<br>***T&AM MPW Program*** | **Session 25:**<br>Phased Array Technology | **Session 26:**<br>Side-Channel Analysis | **Session 27:**<br>NGMM | **Session 28:**<br>III-N Power Electronics | **Session 29:**<br>Approaches to Advanced Designs on Intel 18A Technology | **Session 30:**<br>Enabling Photonic Devices | 1:30–3:10 pm | |
| | BREAK<br>3:10–3:30 pm | | | **BREAK (Exhibit Hall I-2)** | | | | | | | | | BREAK<br>3:10–3:30 pm | |
| | 3:30–5:10 pm | | | .............................. | .............................. | **Panel:**<br>***Intel 18A Technology: The DIB Design Experience*** | **Session 31:**<br>THREADS | **Session 32:**<br>Fuzzing Techniques for Security Verification | **Session 33:**<br>On-Shore Packaging | **Session 34:**<br>AI for Design | **Session 35:**<br>ASSERT | **Session 36:**<br>Means and Methods to Implement Intelligent Systems | 3:30–5:10 pm | |
| | 6:30–10:30 pm | ⚜ **Mardi Gras World Social Event** ⚜ **(Buy your ticket and join our exclusive second line parade when it steps off from the convention center at 6:30 pm.)** | | | | | | | | | | | 6:30–10:30 pm | |
| **Thursday, March 12** | 8:20–10:00 am | **Registration (8:00 am–3:00 pm)**<br>**Breakfast (8:00–8:30 am)** | .............................. | .............................. | .............................. | **Panel:**<br>***Re-Education & Retention*** | **Session 37:**<br>RF System Application | **Session 38:**<br>Physical Unclonable Functions and Hybrid Circuits | **Session 39:**<br>Advanced Packaging in Defense Applications | **Session 40:**<br>AI for Hardware Security | **Session 41:**<br>Radiation Hardened By Design | .............................. | 8:20–10:00 am | **Thursday, March 12** |
| | BREAK<br>10:00–10:30 am | | .............................. | **BREAK** | | | | | | | | | BREAK<br>10:00–10:30 am | |
| | 10:30 am–12:00 pm | | **Poster Session (10:30 am–12:00 pm)** | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | .............................. | 10:30 am–12:00 pm | |
| | LUNCH<br>12:00–1:30 pm | | .............................. | **LUNCH BUFFET (Exhibit Hall I-2)** | | | | | | | | | LUNCH<br>12:00–1:30 pm | |
| | 1:30–3:10 pm | | .............................. | .............................. | .............................. | **Panel:**<br>***Is "Industry Standards & Tools for Security" an Oxymoron?*** | **Session 42:**<br>RF Signal Processing | **Session 43:**<br>Fault Injection Analysis | **Session 44:**<br>RF Simulation, Modeling & Design | **Session 45:**<br>AI Processing & Applications I | **Session 46:**<br>Radiation Hardened Technologies and Systems | **Session 47:**<br>WBG/UWBG Substates & Technology | 1:30–3:10 pm | |
| | BREAK<br>3:10–3:30 pm | | .............................. | **BREAK (2nd Floor Foyer)** | | | | | | | | | BREAK<br>3:10–3:30 pm | |
| | 3:30–5:10 pm | .............................. | .............................. | .............................. | .............................. | .............................. | **Session 48:**<br>MMICs | **Session 49:**<br>Artificial Intelligence for Cyber Secure Microelectronics | **Session 50:**<br>Security Frameworks and Policies | **Session 51:**<br>AI Processors & Applications II | .............................. | **Session 52:**<br>Materials for Devices | 3:30–5:10 pm | |